



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

10 Apr 2008

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #16112

TITLE: Move of IC T092 Assembly and Test to Dalian, China

PROPOSED FIRST SHIP DATE: Aug 10, 2008

AFFECTED CHANGE CATEGORY: Assembly, Test

AFFECTED PRODUCT DIVISION: Analog Power Management

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your Local ON Semiconductor Sales Office or Jaroslav Supina
<Jaroslav.Supina@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

The IC T092 products are currently assembled at AUK located in Korea. Both assembly and test will be moved to the AUK factory at Dalian, China. The exact same process flow, bill of material and test equipment will be utilized at the new location. There is no change being made to the die or product specifications due to this move.

The AUK facility at Dalian is fully qualified to meet TS16949, ISO9001 & ISO14001.


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QUALIFICATION PLAN:

All Reliability testing will be performed according to the requirements of AEC-Q100 specification.

Qualification Vehicle: LM2931AZ-5.0G

Number of Qualification lots: 3

AEC #	Test	Ref	Test Conditions	End Point Requirements	Sample Size	# of Lots	Total Units	Comments
1	Electrical Test	ON Data Sheet	ON Product Specification	See Below	All Devices			
2	HTSL	JA103	150°C for 1000 hrs	Test @ R, H	80	3	240	Test at initial/endpoint at room and hot temperatures
3	TC	JA104	-65°C to +150°C for 500 cycles	Test @ R, H	80	3	240	Test at initial/endpoint at room and hot temperatures
4	AC	JA102	121°C/100%RH /15 psig for 96 hrs	Test @ R, H	80	3	240	Test at initial/endpoint at room and hot temperatures
5	HAST	JA101	130°C/85% RH for 96 hrs	Test @ R, H	80	3	240	Test at initial/endpoint at room and hot temperatures
6	BPS	M883 Method 2011	Wire Bond Pull Strength, Condition C	3gm Pull Force Min After TC	30 bonds from 5 units	1	5	
7	BS	AEC-Q100-001	Bond Shear Test	Cpk 1.33	30 bonds from 5 units	1	5	
8	SD	JB102	Solderability		15	1	15	260°C
9	PD	JB100	Per case outline	Ppk>1.66 Cpk>1.33	10	3	30	
10	LI	JB105	Lead Integrity (Not required for surface mount devices)		10 leads from 5 units	1	5	
11	ED	ON Data Sheet	Electrical Distributions	Cpk > 1.67	30	3	90	room, hot, cold



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AFFECTED DEVICE LIST:

PART

LM285Z-1.2G	MC34064P-5RAG
LM285Z-1.2RAG	MC34064P-5RMG
LM285Z-2.5G	MC34064P-5RPG
LM285Z-2.5RAG	MC34164P-3G
LM285Z-2.5RPG	MC34164P-3RPG
LM2931AZ-5.0G	MC34164P-5G
LM2931AZ-5.0RAG	MC34164P-5RAG
LM2931AZ-5.0RPG	MC34164P-5RPG
LM2931Z-5.0G	MC78L05ABPG
LM2931Z-5.0RAG	MC78L05ABPRAG
LM2931Z-5.0RPG	MC78L05ABPREG
LM317LBZG	MC78L05ABPRMG
LM317LBZRAG	MC78L05ACPG
LM317LBZRPG	MC78L05ACPRAG
LM317LZG	MC78L05ACPREG
LM317LZRAG	MC78L05ACPRMG
LM317LZREG	MC78L05ACPRPG
LM317LZRMG	MC78L08ABPG
LM317LZRPG	MC78L08ABPRAG
LM385BZ-1.2G	MC78L08ABPRPG
LM385BZ-1.2RAG	MC78L08ACPG
LM385BZ-2.5G	MC78L08ACPRAG
LM385BZ-2.5RAG	MC78L08ACPREG
LM385Z-1.2G	MC78L08ACPRPG
LM385Z-1.2RAG	MC78L09ABPRAG
LM385Z-1.2RPG	MC78L09ABPRPG
LM385Z-2.5G	MC78L09ACPG
LM385Z-2.5RPG	MC78L12ABPG
LP2950ACZ-3.0G	MC78L12ABPRPG
LP2950ACZ-3.0RAG	MC78L12ACPG
LP2950ACZ-3.3G	MC78L12ACPRAG
LP2950ACZ-3.3RAG	MC78L12ACPREG
LP2950ACZ-5.0G	MC78L12ACPRMG
LP2950ACZ-5.0RAG	MC78L12ACPRPG
LP2950CZ-3.0G	MC78L15ABPG
LP2950CZ-3.0RAG	MC78L15ABPRAG
LP2950CZ-3.3G	MC78L15ABPRPG
LP2950CZ-3.3RAG	MC78L15ACPG
LP2950CZ-5.0G	MC78L15ACPRAG
LP2950CZ-5.0RAG	MC78L15ACPRPG
LP2950CZ-5.0RPG	MC78L18ABPG
MC33064P-5G	MC78L18ACPG
MC33064P-5RAG	MC78L18ACPRAG
MC33064P-5RPG	MC78L18ACPRMG
MC33164P-3G	MC78L18ACPRPG
MC33164P-3RAG	MC78L24ABPG
MC33164P-3RPG	MC78L24ACPG
MC33164P-5G	MC78L24ACPRAG
MC33164P-5RAG	MC78L24ACPRPG
MC33164P-5RPG	MC79L05ABPG
MC34064P-5G	MC79L05ABPRAG

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MC79L05ACPG	TL431CLPRPG
MC79L05ACPRAG	TL431ILPG
MC79L05ACPRMG	TL431ILPRAG
MC79L05ACPRPG	TL431ILPRPG
MC79L12ABPG	TLV431ALPG
MC79L12ABPRAG	TLV431ALPRAG
MC79L12ACPG	TLV431ALPREG
MC79L12ACPRAG	TLV431ALPRMG
MC79L12ACPRPG	TLV431ALPRPG
MC79L15ABPG	TLV431BLPG
MC79L15ABPRPG	TLV431BLPRAG
MC79L15ACPG	TLV431BLPREG
MC79L15ACPRAG	TLV431BLPRMG
MC79L15ACPRPG	TLV431BLPRPG
MC79L18ABPRPG	TYA33164P-5RPG
MC79L18ACPG	
MC79L24ABPG	
MC79L24ACPG	
MC79L24ACPRMG	
MC79L24ACPRPG	
NCP100ALPRPG	
NCV317LBZG	
NCV317LBZRAG	
NCV33064P-5RAG	
NCV33064P-5RPG	
NCV78L05ABPG	
NCV78L05ABPRAG	
NCV78L05ABPREG	
NCV78L05ABPRMG	
NCV78L05ABPRPG	
NCV78L12ABPG	
NCV78L24ABPRPG	
TL431ACLPG	
TL431ACLPRAG	
TL431ACLPREG	
TL431ACLPRPG	
TL431AILPG	
TL431AILPRAG	
TL431AILPRMG	
TL431AILPRPG	
TL431BCLPG	
TL431BCLPRAG	
TL431BCLPREG	
TL431BCLPRMG	
TL431BILPG	
TL431BILPRAG	
TL431BVLPG	
TL431BVLPRAG	
TL431CLPG	
TL431CLPRAG	
TL431CLPREG	
TL431CLPRMG	